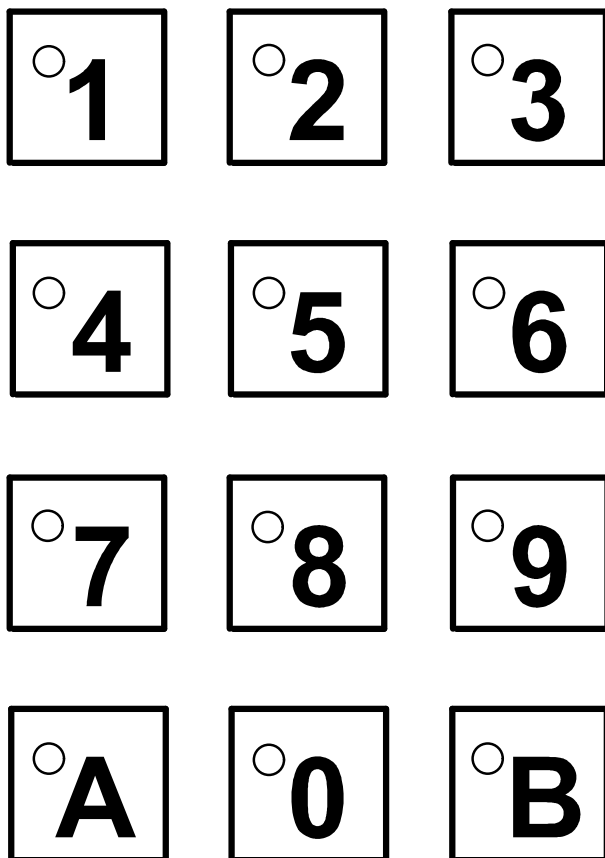
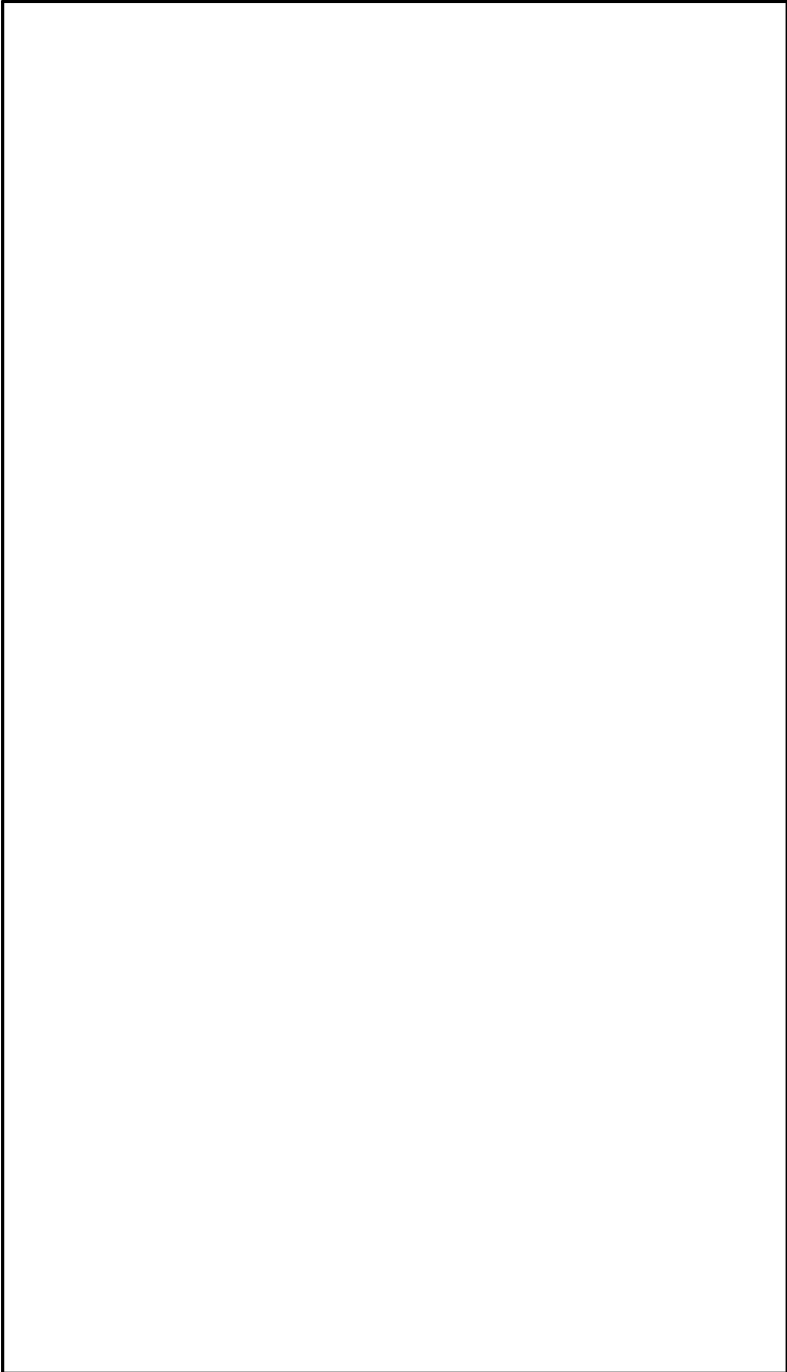


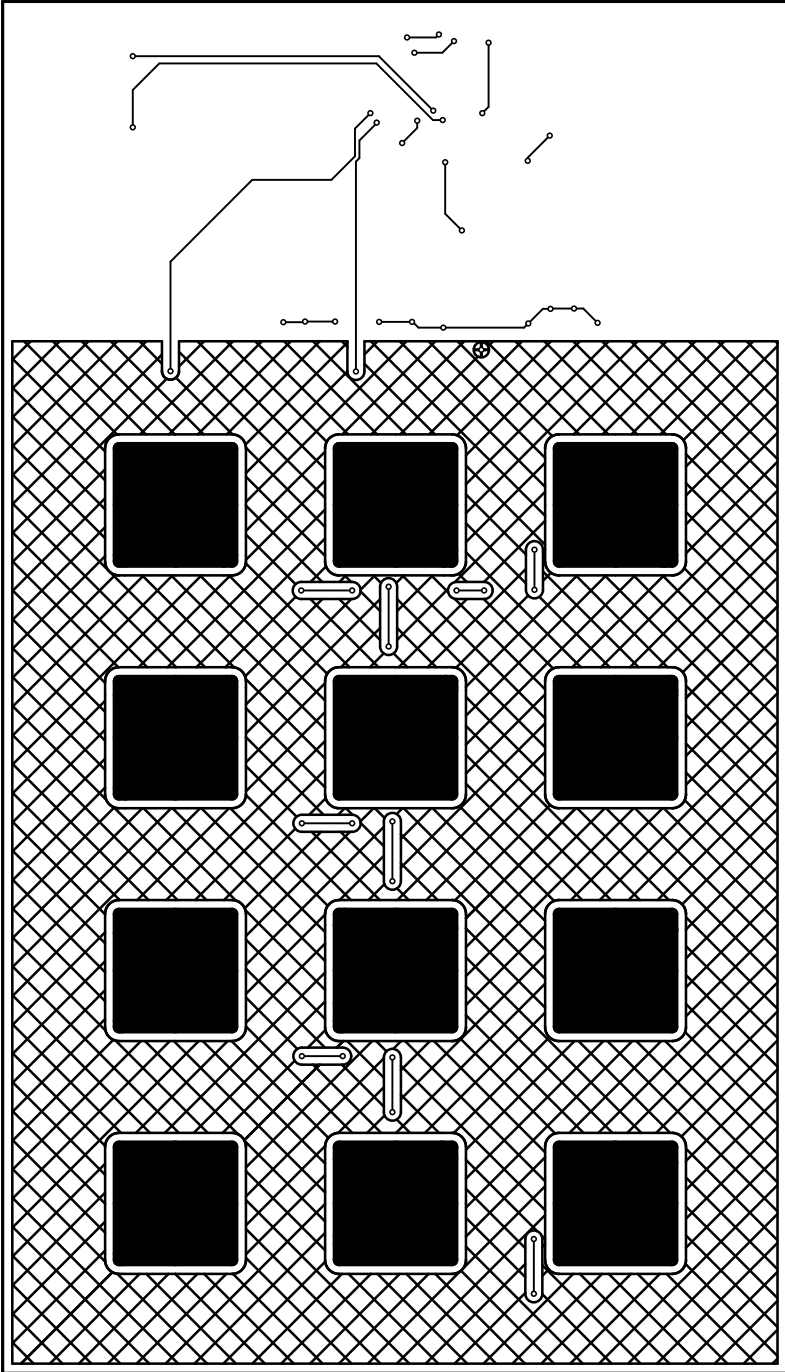
**MSP430 MCU**  
**CapTivate™ Technology**  
Liquid Tolerant Capacitive Touch Keypad Reference Design  
TIDM-1021



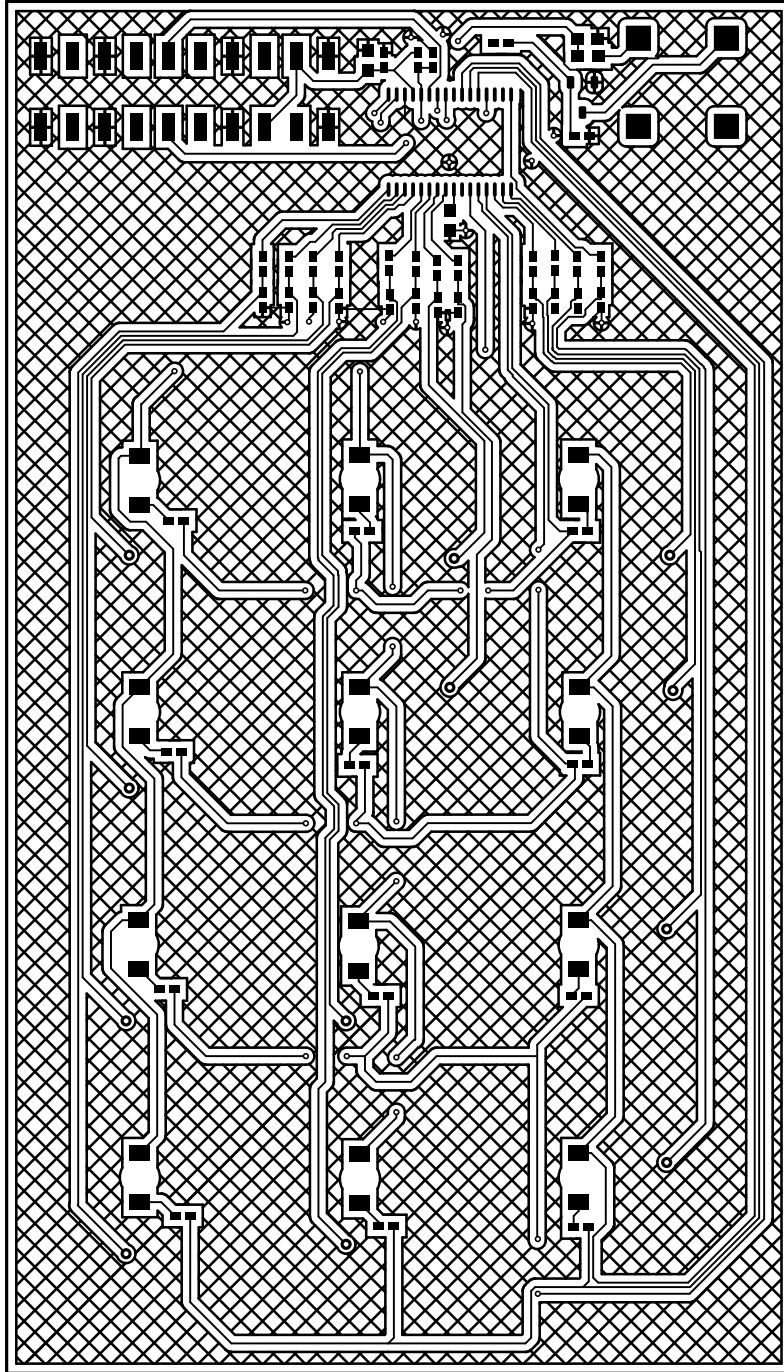
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDM-1021	REV: 1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDM-1021		
PLOT NAME = Top Overlay	GENERATED : 7/19/2018	6:56:13 PM	TEXAS INSTRUMENTS



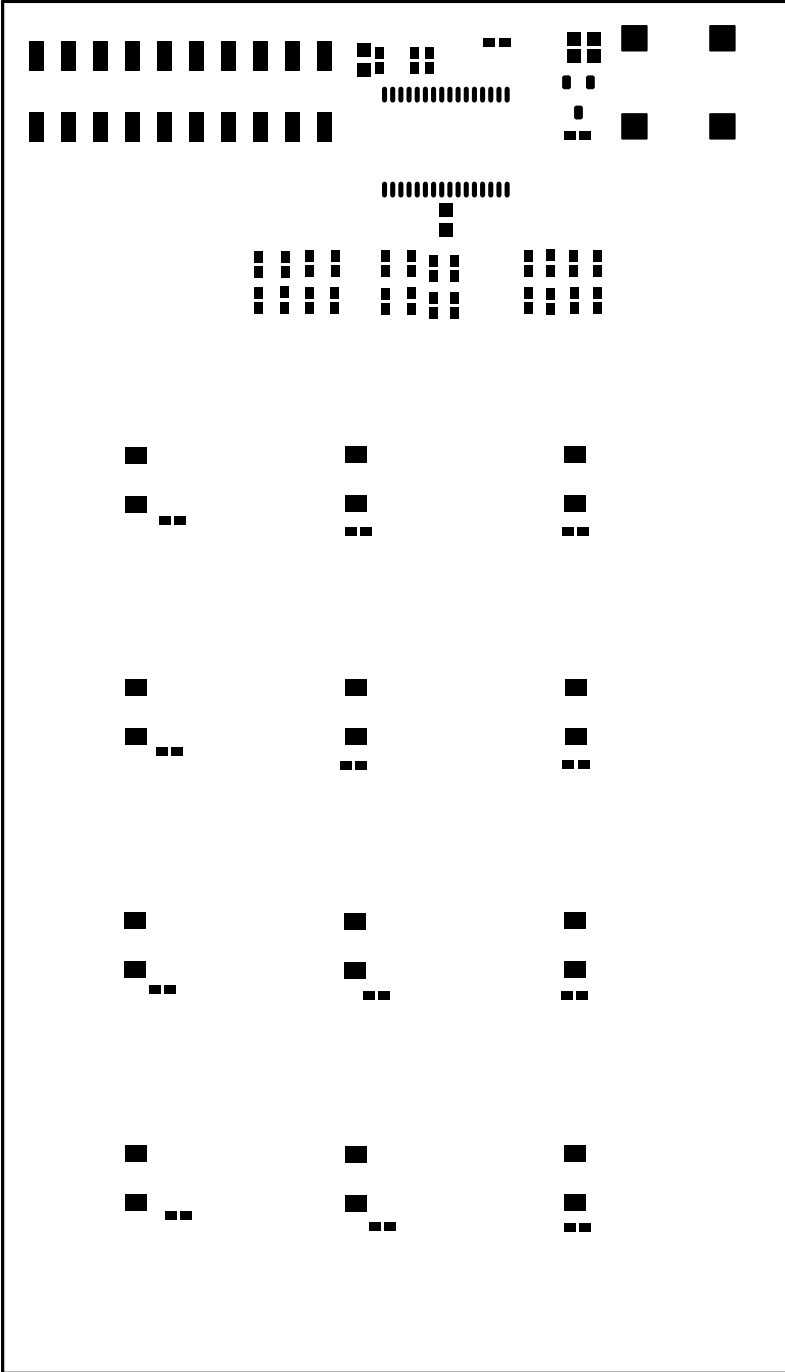
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDM-1021	REV: 1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDM-1021		
PLOT NAME = Top Solder Mask	GENERATED : 7/19/2018 6:56:14 PM	TEXAS INSTRUMENTS	



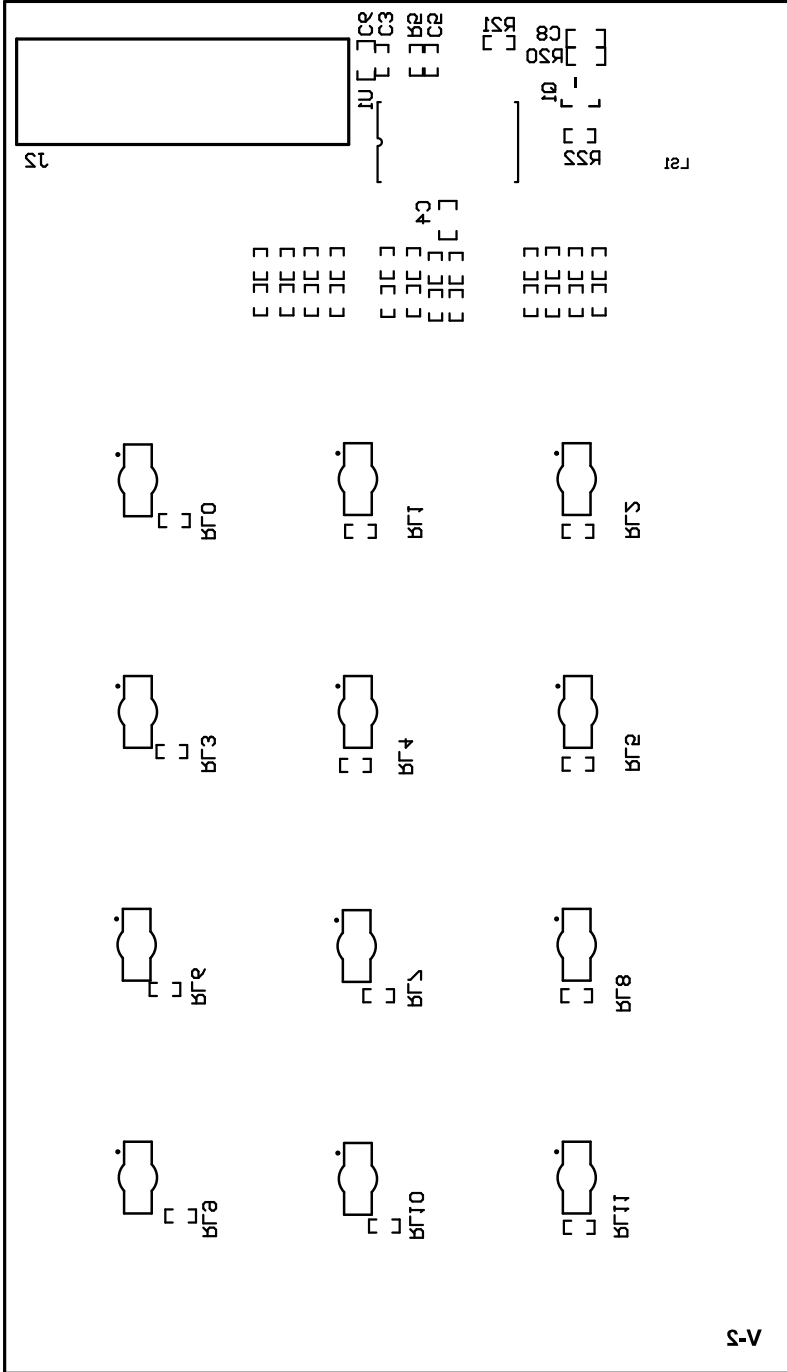
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDM-1021	REV: 1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDM-1021		
PLOT NAME = Top Layer	GENERATED : 7/19/2018	6:56:15 PM	TEXAS INSTRUMENTS



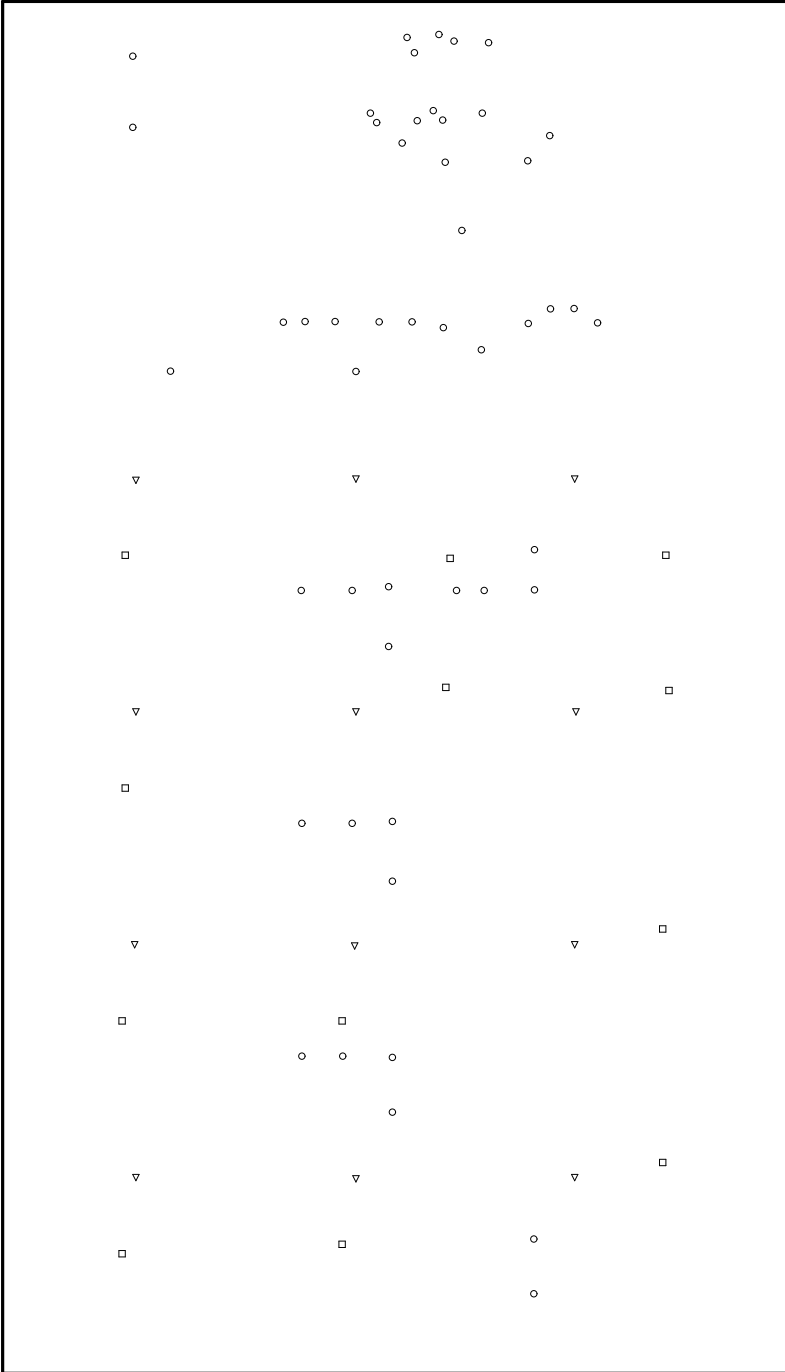
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDM-1021	REV: 1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDM-1021		
PLOT NAME = Bottom Layer	GENERATED : 7/19/2018	6:56:15 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDM-1021	REV: 1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDM-1021		
PLOT NAME = Bottom Solder Mask	GENERATED : 7/19/2018	6:56:16 PM	TEXAS INSTRUMENTS

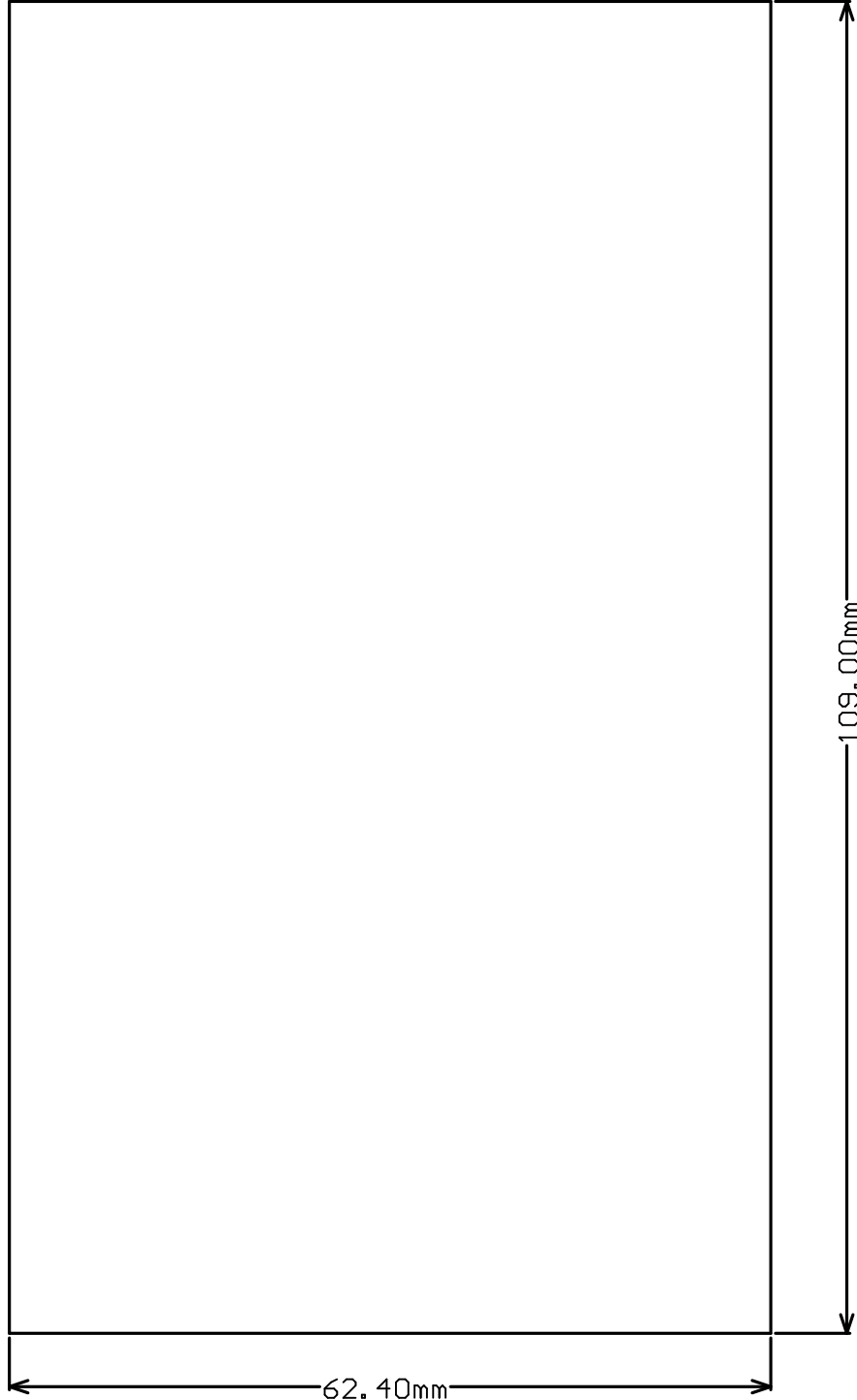


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDM-1021	REV: 1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDM-1021		
PLOT NAME = Bottom Overlay	GENERATED : 7/19/2018	6:56:17 PM	TEXAS INSTRUMENTS



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
▽	12	2.000mm (78.74mil)	NPTH	Round	Top Layer - Bottom Layer	
○	49	0.254mm (10.00mil)	PTH	Round	Top Layer - Bottom Layer	
□	12	0.381mm (15.00mil)	PTH	Round	Top Layer - Bottom Layer	
	73 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDM-1021	REV: 1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDM-1021		
PLOT NAME = Drill Drawing	GENERATED : 7/19/2018	6:56:19 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDM-1021	REV: 1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDM-1021		
PLOT NAME = BoardDimensions	GENERATED : 7/19/2018	6:56:22 PM	TEXAS INSTRUMENTS



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